



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

Compaq CQ2000 PC Series

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	system fan	1
Components and parts containing toner and ink,	Include the cartridges, print heads, tubes, vent	0

including liquids, semi-liquids (gel/paste) and toner	chambers, and service stations.	
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 T15 screw driver	Φ5
Description #1 Phillips screw driver	2#
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel
2. Remove front bezel
3. Remove ODD cage
4. Remove MB and take off CMOS battery
5. Remove front IO and CR
6. tooling list
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



1 Remove access panel

Rotate screw to open the cover use T15 screw driver



2 Remove front bezel

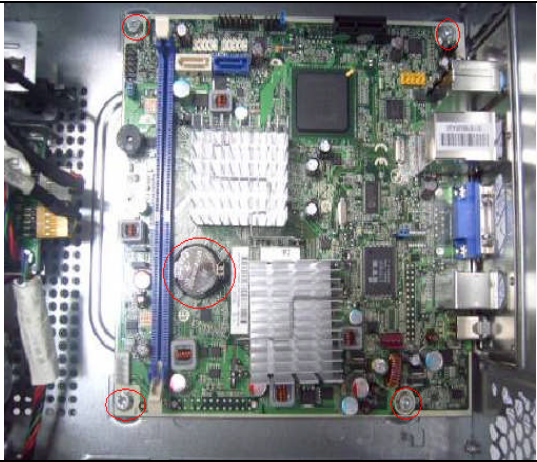
Pull up the latch of front bezel and rotate the front bezel

Use hand



3 Remove ODD cage

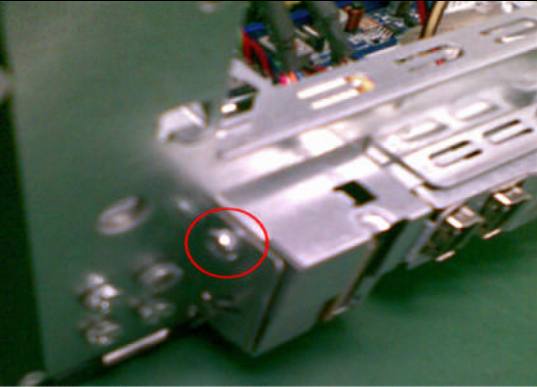
Rotate screw to open the ODD cage use T15 screw driver



4 Remove MB and Take off CMOS battery

Use T15 screw driver to rotate 4 screw of MB

Pull the battery holder as shown in the photo, and then the battery will off the PCA



5 Remove front IO and CR.

Rotate the screw driver to take off the screws of front IO and CR. Use T15 screw driver





6 screw driver

T15 screw driver

Phillips screw driver **2#**